

TMAX-1770-XXX-M M lded P e I d c

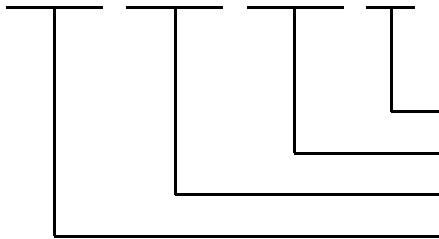
Features

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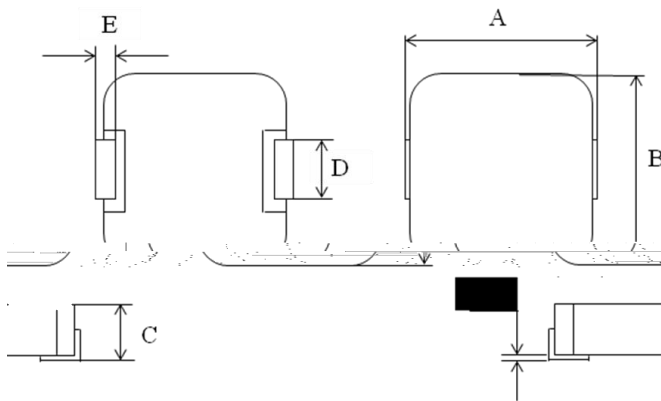
Applications

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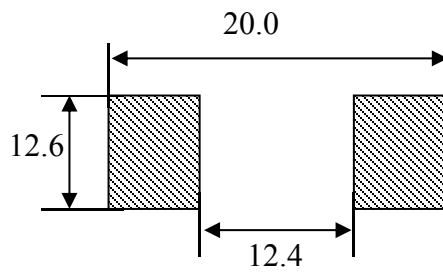
Product Description



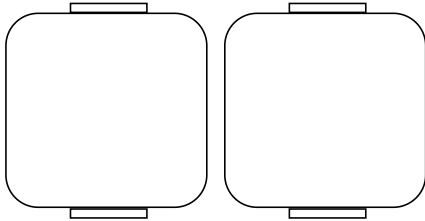
Dimensions



	17.5 Max.
	17.15 Max.
	7.0 Max.
	11.8±0.3
	2.5±0.5
	0~0.30

Recommend Land Pattern Dimensions**Marking**

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-

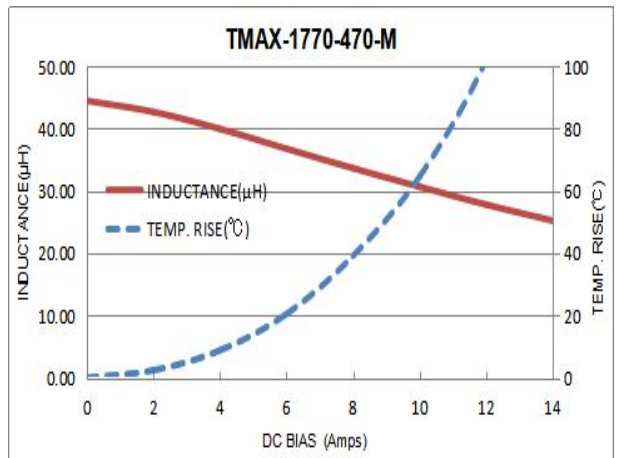
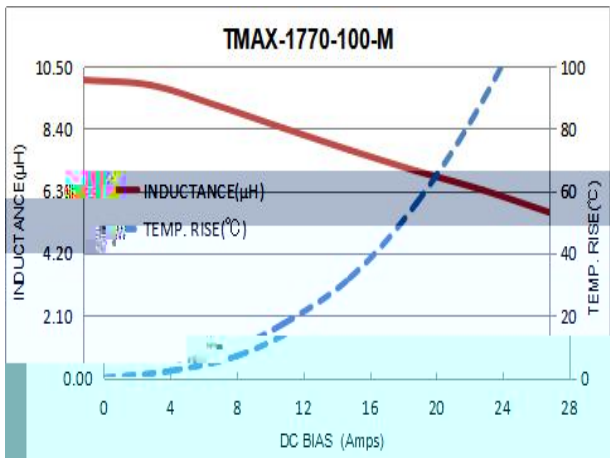
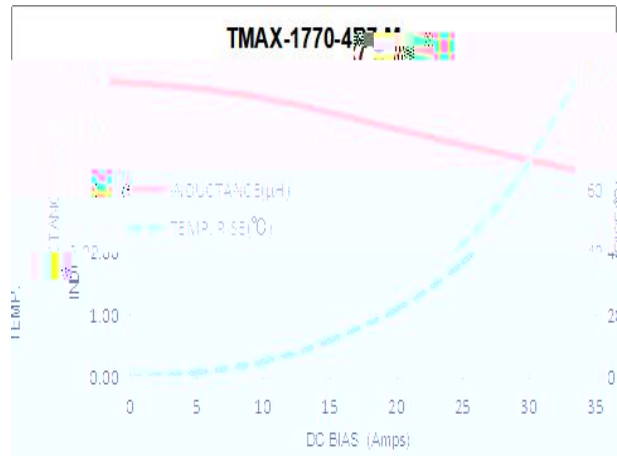
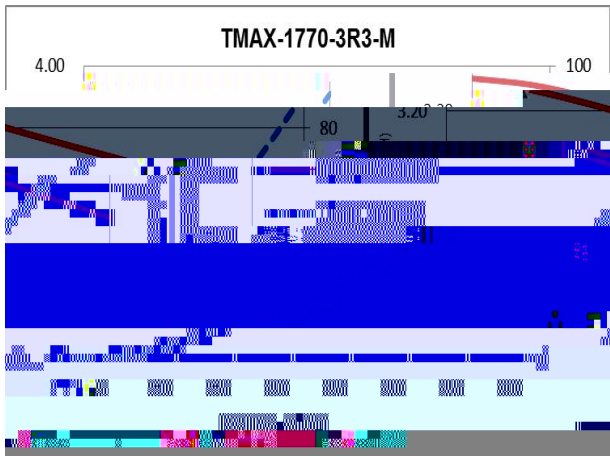


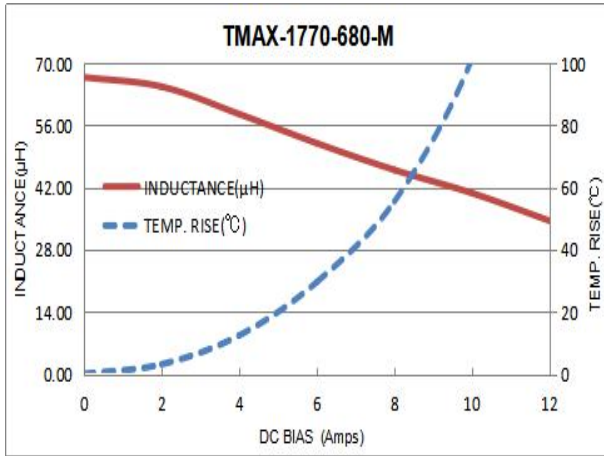
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Notes:

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Inductance and Temperature Rise vs. DC Current





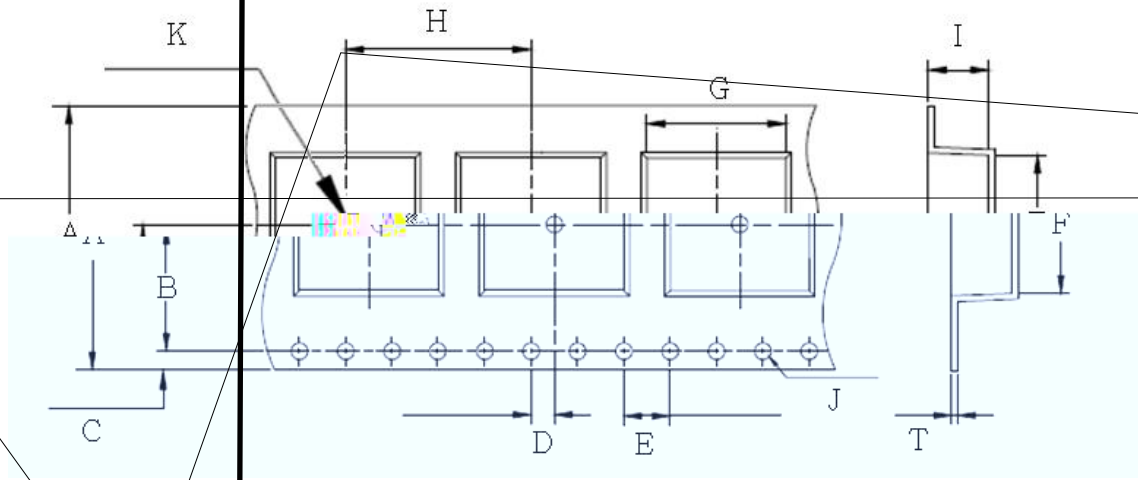
Reliability:

Item	Test Method	Specification and Requirement
	\pm \pm °C \pm	
		\pm

Reliability:

Item	Test Method	Specification and Requirement
	\pm \pm \rightarrow \rightarrow \pm \pm \rightarrow	
	\pm	\pm
	\pm	
	\pm	
	\pm	

Packaging Dimensions



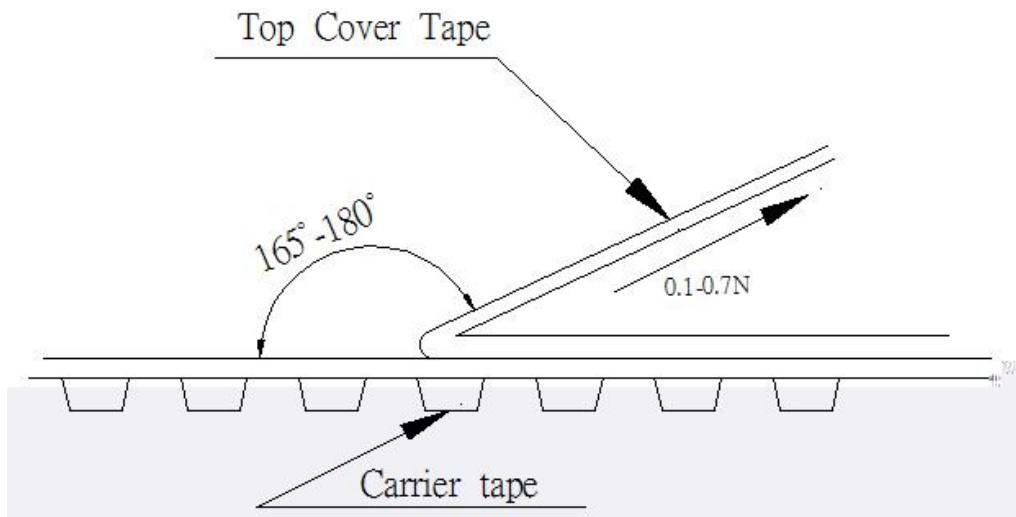
±	±	±	±	±	±	±
±	±	±	±	±	±	±



±	±	

Peeling of top cover tape

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-



Reflow Profile

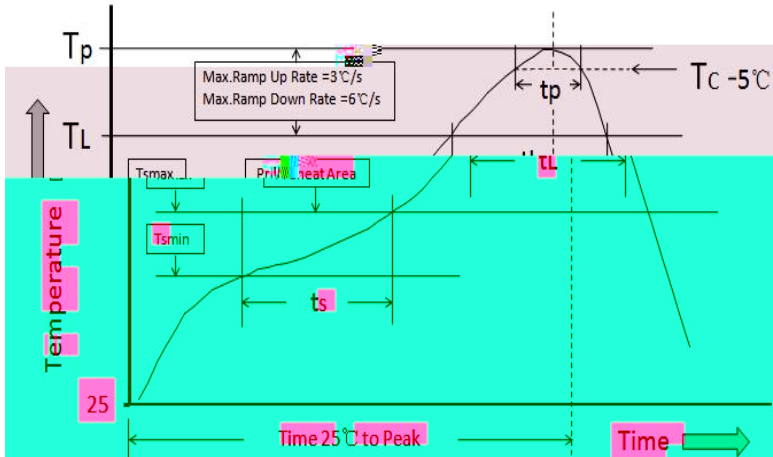


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≧350
<	°C	°C
≧	°C	°C

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<	°C	°C	°C
	°C	°C	°C
	°C	°C	°C

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder
	°C	°C
	°C	°C
	°C	°C
	°C	°C
	°C	°C
°C		
	°C	°C
°C		

Numbers of taping

-

Label marking

-
-

Production Label

- ✓
- ✓
- ✓
- ✓
- ✓

Shipping Label

- ✓
- ✓
- ✓
- ✓
- ✓

Care note for use

➤ **Storage Condition**

➤ **Use Temperature**

- ✓

✘ **Model**

- ✓

- ✓

Care note for Safety